

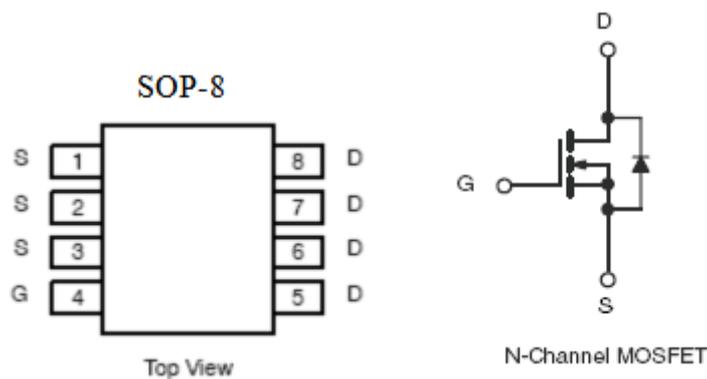
1. Features

- n $R_{DS(on)}=14.5m\Omega(\text{typ})@ V_{GS}=10\text{ V}$
- n Super low gate charge
- n Green device available
- n Excellent Cdv/dt effect decline
- n Advanced high cell density trench technology

2. Description

The KIA4603A is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The KIA4603A meet the RoHs and Green Product requirement.

3. Symbol



4. Absolute maximum ratings

($T_A=25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | Rating | Units |
|---|-----------------|------------------------|--------------------|
| Drain-source voltage | V_{DSS} | 30 | V |
| Gate-source voltage | V_{GS} | ± 20 | V |
| Continuous drain current $V_{GS}@10V^1$ | I_D | $T_A=25^\circ\text{C}$ | 7.0 |
| | | $T_A=70^\circ\text{C}$ | 5.6 |
| Pulsed drain current ² | I_{DM} | 35 | A |
| Single pulse avalanche energy ³ | EAS | 20 | mJ |
| Avalanche current | I_{AS} | 20 | A |
| Total power dissipation ⁴ | P_D | 1.5 | W |
| Junction and storage temperature range | T_J, T_{STG} | -55 to 150 | $^\circ\text{C}$ |
| Thermal resistance-junction to ambient ¹ | $R_{\theta JA}$ | 85 | $^\circ\text{C/W}$ |
| Thermal resistance-junction to case ¹ | $R_{\theta JC}$ | 25 | $^\circ\text{C/W}$ |

5. Electrical characteristics

(T_J=25°C, unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|---|--------------------------------------|---|-----|-------|-------|-------|
| Drain-Source breakdown voltage | BV _{DSS} | V _{GS} =0V, I _D =-250μA | 30 | - | - | V |
| BV _{DSS} Temperature coefficient | $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Reference to 25°C, I _D =1mA | - | 0.034 | - | V/°C |
| Drain-Source Leakage Current | I _{DSS} | V _{DS} =24V, V _{GS} =0V, T _J =25°C | - | - | 1 | μA |
| | | V _{DS} =24V, V _{GS} =0V, T _J =55°C | - | - | 5 | |
| Gate-source leakage current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 1.2 | 1.5 | 2.5 | V |
| V _{GS(th)} Temperature coefficient | $\Delta V_{GS(th)}$ | | - | 3.84 | - | mV/°C |
| Static drain-source on- resistance ² | R _{DS(on)} | V _{GS} =10V, I _D =7A | - | 14.5 | 18 | mΩ |
| | | V _{GS} =4.5V, I _D =4A | - | 20 | 26 | |
| Forward transconductance | g _{FS} | V _{DS} =5V, I _D =7A | - | 6.2 | - | S |
| Diode forward voltage ² | V _{SD} | V _{GS} =0V, I _S =1A, T _J =25°C | - | - | 1.2 | V |
| Gate resistance | R _g | V _{DS} =0V, V _{GS} =0V, f=1MHz | - | 1.04 | 2.1 | Ω |
| Total gate charge(4.5V) | Q _g | V _{DS} =15V, V _{GS} =4.5V I _D =7A | - | 6 | 8.4 | nC |
| Gate-source charge | Q _{gs} | | - | 2.2 | 3.1 | |
| Gate-drain charge | Q _{gd} | | - | 2 | 2.8 | |
| Turn-on delay time | t _{d(on)} | V _{DD} =15V, R _G =3.3Ω, V _{GS} =10V I _D =7A | - | 1.2 | 2.4 | ns |
| Rise time | t _r | | - | 40 | 72 | |
| Turn-off delay time | t _{d(off)} | | - | 18 | 36 | |
| Fall time | t _f | | - | 7.2 | 14.4 | |
| Input capacitance | C _{iss} | V _{GS} =0V, V _{DS} =15V F=1.0MHZ | - | 583 | 816.2 | pF |
| Output capacitance | C _{oss} | | - | 77 | 107.8 | |
| Reverse transfer capacitance | C _{rss} | | - | 59 | 82.6 | |
| Diode characteristics | | | | | | |
| Continuous source current ^{1,5} | I _S | V _G =V _D =0V, Force current | - | - | 7 | A |
| Pulsed source current ^{2,5} | I _{SM} | | - | - | 35 | A |
| Reverse recovery time | t _{rr} | I _F =7A, di/dt=100A/us, T _J =25°C | - | 7.2 | - | nS |
| Reverse recovery charge | Q _{rr} | | - | 2.9 | - | nC |

Note:1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed, pulse width ≤300us, duty cycle ≤2%.

3. The EAS data shows Max.rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH. I_{AS}=20A.

4. The power dissipation is limited by 150 °C junction temperature.

5. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

6. Test circuits and waveforms

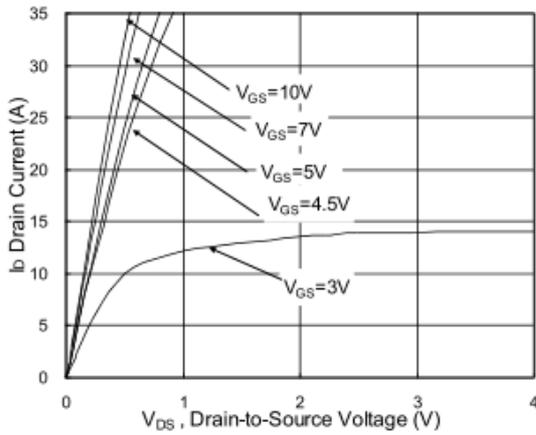


Fig.1 Typical Output Characteristics

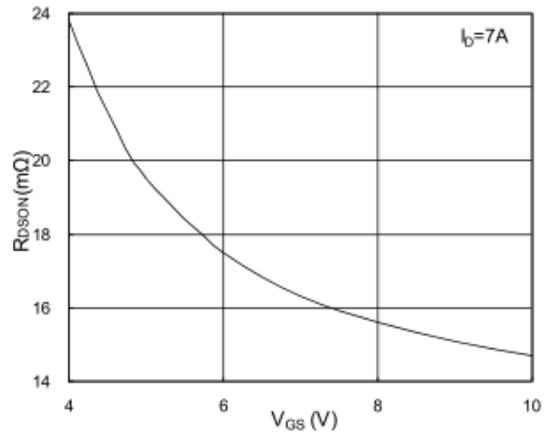


Fig.2 On-Resistance vs. Gate-Source

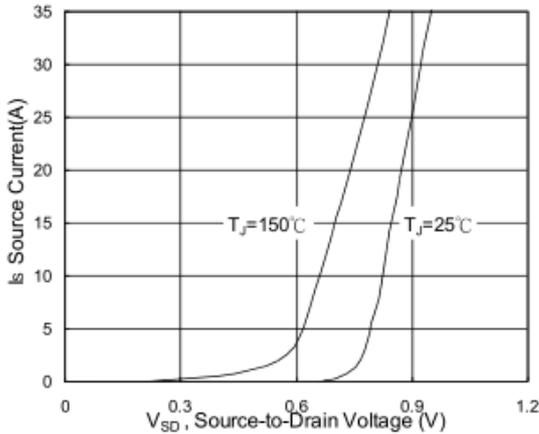


Fig.3 Forward Characteristics Of Reverse

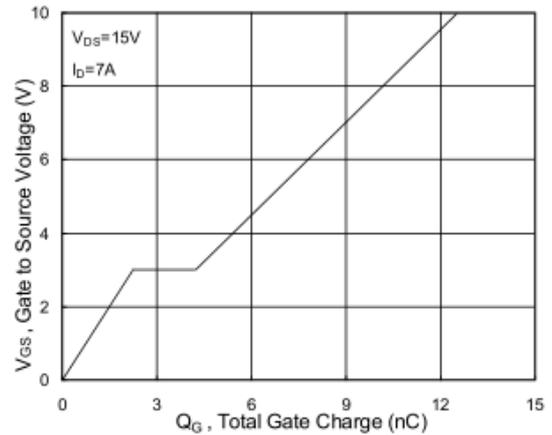


Fig.4 Gate-Charge Characteristics

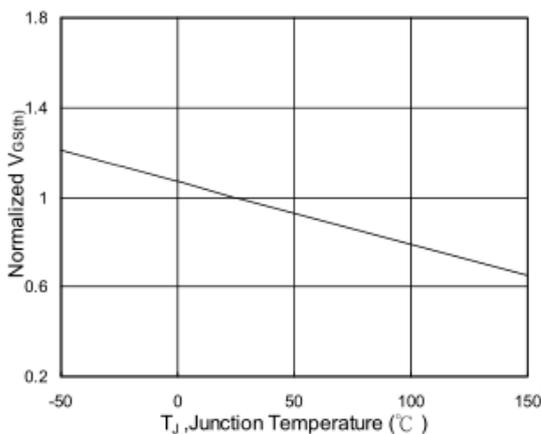


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

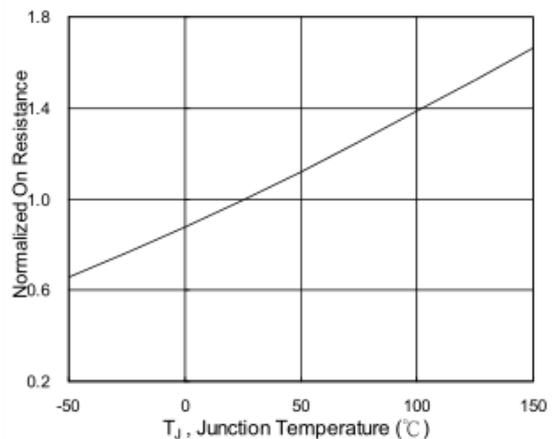


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

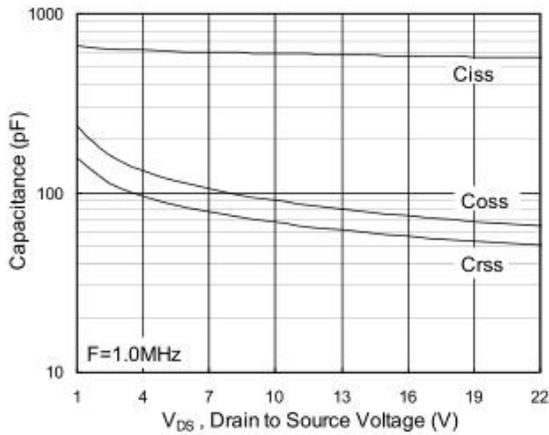


Fig.7 Capacitance

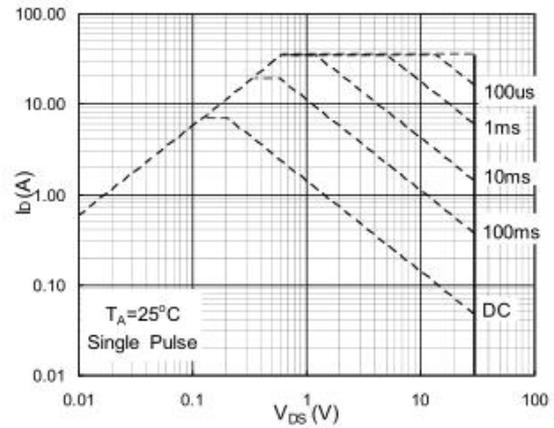


Fig.8 Safe Operating Area

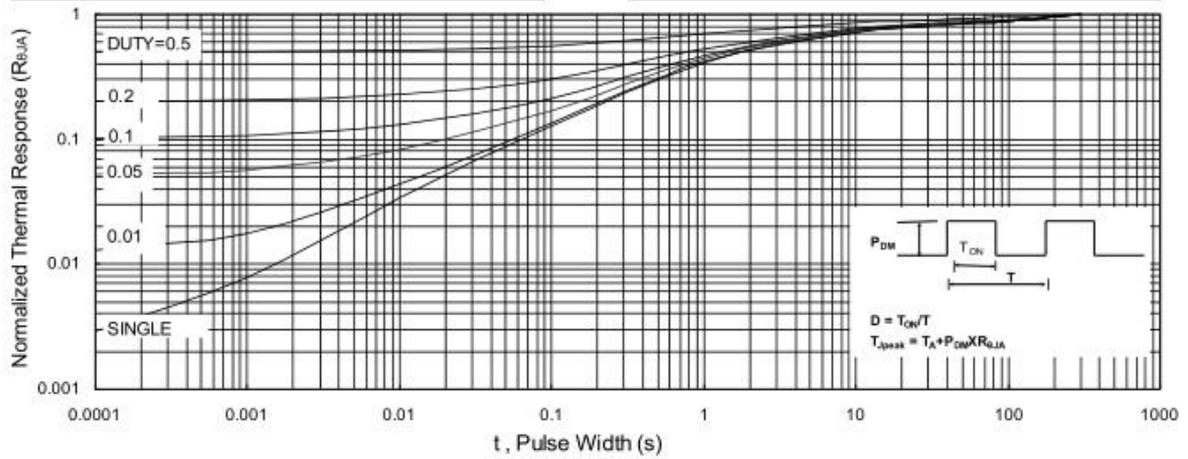


Fig.9 Normalized Maximum Transient Thermal Impedance

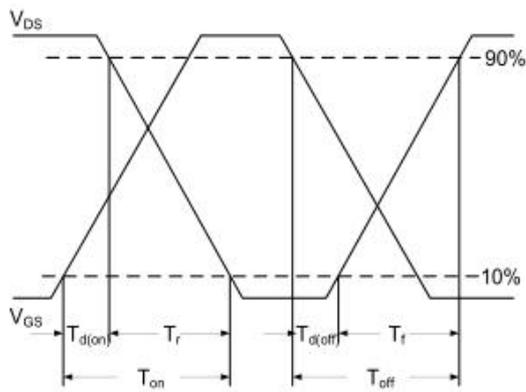


Fig.10 Switching Time Waveform

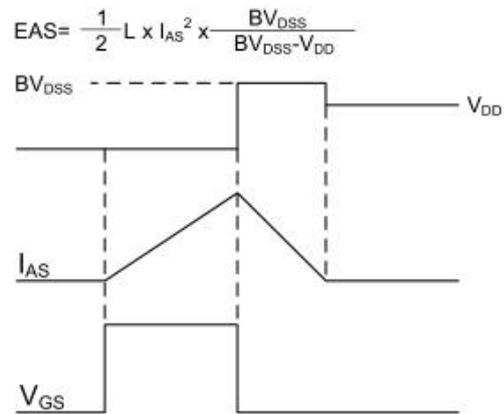


Fig.11 Unclamped Inductive Switching Waveform

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